IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Kishore K. Chakravorty et al.

Ile: CALECTRONIC ASSEMBLY COMPRISING CERAMIC/ORGANIC HYBRID SUBSTRATE

JAN 0 7 2004 WITH EMBEDDED CAPACITORS AND METHODS OF MANUFACTURE

tocket No.: 884.315US1

Files August 30, 2000 Examiner: Thanh S. Phan

Customer No.: 21186

Serial No : 09/650566

Due Date: January 3, 2004 (Saturday)

Group Art Unit: 2841 Confirmation No.: 8541

MS Non-Fee Amendment

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

 \underline{X} A return postcard.

- \underline{X} An Amendment and Response Under 37 CFR 1.111 (19 Pages).
- X An Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 1 cited documents.
- \underline{X} A check in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

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(GENERAL)

S/NS 9/650,566

PATENT

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Applicants:

Kishore K. Chakravorty et al.

Examiner: Thanh S. Phan

Serial No.:

09/650,566

Group Art Unit: 2841

Filed:

August 30, 2000

Docket No.: 884.315US1

Title:

ELECTRONIC ASSEMBLY COMPRISING CERAMIC/ORGANIC HYBRID

SUBSTRATE WITH EMBEDDED CAPACITORS AND METHODS OF

MANUFACTURE

Assignee:

Intel Corporation

Customer No. 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants have reviewed the Office Action mailed on October 3, 2003. Please amend the above-identified patent application as follows.